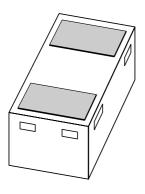
# DISCRETE SEMICONDUCTORS

# DATA SHEET



# **BAT54L**Schottky barrier diode

**Product specification** 

2003 Jun 23





## Schottky barrier diode

BAT54L

#### **FEATURES**

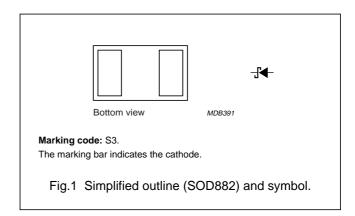
- · Low forward voltage
- Leadless ultra small plastic package (1 mm × 0.6 mm × 0.5 mm)
- Boardspace 1.17 mm<sup>2</sup> (approx. 10% of SOT23)
- Power dissipation comparable to SOT23.

#### **APPLICATIONS**

- · Ultra high-speed switching
- · Voltage clamping
- · Protection circuits
- Mobile communication, digital (still) cameras, PDAs and PCMCIA cards.

#### **DESCRIPTION**

Planar Schottky barrier diode encapsulated in a SOD882 leadless ultra small plastic package.



#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>R</sub>	continuous reverse voltage		_	30	V
I <sub>F</sub>	continuous forward current		_	200	mA
I <sub>FRM</sub>	repetitive peak forward current	$t_p \le 1s; \ \delta \le 0.5$	_	300	mA
I <sub>FSM</sub>	non-repetitive peak forward current	t <sub>p</sub> < 10 ms	_	600	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	_	250	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
T <sub>i</sub>	junction temperature		_	150	°C

#### Note

1. Refer to SOD882 standard mounting conditions (footprint), FR4 printed-circuit board with 60 μm copper strip line.

# Schottky barrier diode

BAT54L

#### **ELECTRICAL CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
V <sub>F</sub>	forward voltage	see Fig.2		
		I <sub>F</sub> = 0.1 mA	240	mV
		I <sub>F</sub> = 1 mA	320	mV
		I <sub>F</sub> = 10 mA	400	mV
		I <sub>F</sub> = 30 mA	500	mV
		I <sub>F</sub> = 100 mA	800	mV
I <sub>R</sub>	continuous reverse current	V <sub>R</sub> = 25 V; see Fig.3; note 1	2	μΑ
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 1 V; f = 1 MHz; see Fig.4	10	pF

#### Note

1. Pulse test:  $t_p$  = 300  $\mu$ s;  $\delta$  = 0.02.

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	500	K/W

#### Note

1. Refer to SOD882 standard mounting conditions (footprint), FR4 printed-circuit board with 60 μm copper strip line.

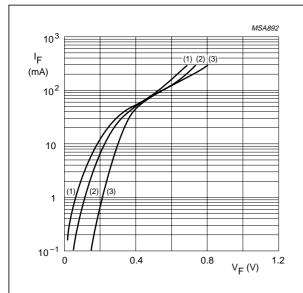
#### Soldering

Reflow soldering is the only recommended soldering method.

# Schottky barrier diode

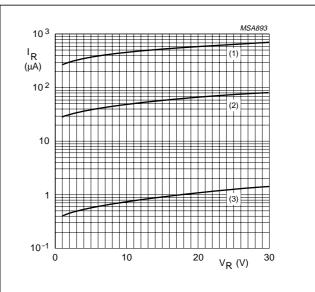
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#### **GRAPHICAL DATA**



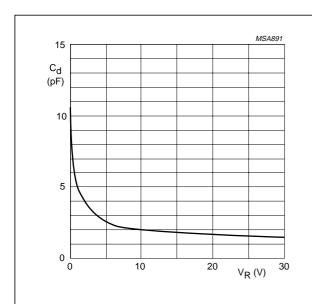
- (1)  $T_{amb} = 125 \,^{\circ}C$ .
- (2)  $T_{amb} = 85 \, ^{\circ}C$ .
- (3)  $T_{amb} = 25 \, ^{\circ}C$ .

Fig.2 Forward current as a function of forward voltage; typical values.



- (1)  $T_{amb} = 125 \, ^{\circ}C$ .
- (2)  $T_{amb} = 85 \, ^{\circ}C$ .
- (3)  $T_{amb} = 25 \,^{\circ}C$ .

Fig.3 Reverse current as a function of reverse voltage; typical values.



 $f = 1 \text{ MHz}; T_{amb} = 25 \,^{\circ}\text{C}.$ 

Fig.4 Diode capacitance as a function of reverse voltage; typical values.

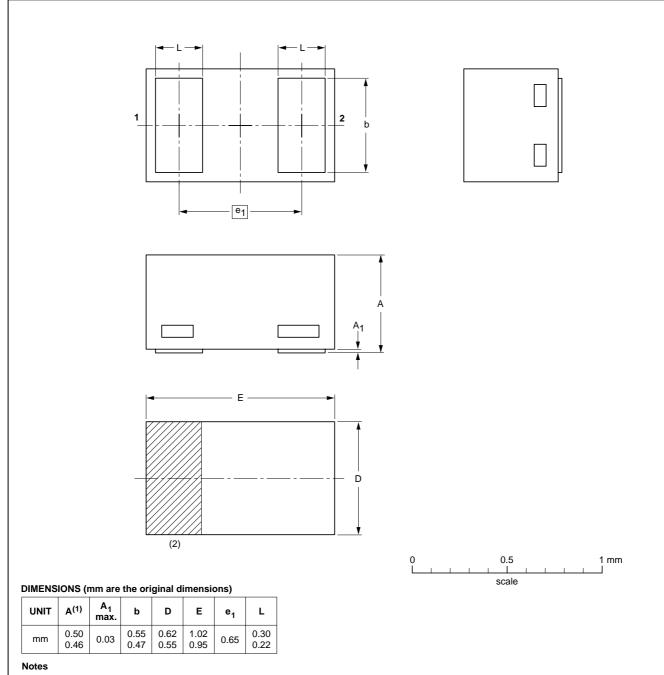
# Schottky barrier diode

BAT54L

#### **PACKAGE OUTLINE**

Leadless ultra small plastic package; 2 terminals; body 1.0 x 0.6 x 0.5 mm

**SOD882** 



- 1. Including plating thickness
- 2. The marking bar indicates the cathode

OUTLINE	REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOD882						<del>03-04-16</del> 03-04-17

### Schottky barrier diode

BAT54L

#### **DATA SHEET STATUS**

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)(3)</sup>	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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BAT54L

NOTES

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